Materials Declaration

Package	PLCC
Body Size	
LeadCount	28
Option	Halide, Pb-free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Silica	86.0	7.05 E-01	616033
Epoxy Resin	7.5	6.15 E-02	53724
Phenol Resin	4.0	3.28 E-02	28652
Epoxy Cresol Novolac	2.0	1.64 E-02	14327
Carbon Black	0.5	4.10 E-03	3582
Subtotal		8.20 E-01	716318

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	99.9	2.91 E-01	253984
Zr	0.1	2.91 E-04	254
Subtotal		2.91 E-01	254238

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	1.48E-03	1293

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	1.41E-02	12351

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.12 E-03	982

Chip

	% of Chip	Weight (g)	PPM
Si	100	1.24E-02	10829

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	75.0	3.42 E-03	2992
Epoxy Resin	20.0	9.13 E-04	798
t-butyl phenyl glycidyl ether	2.5	1.14 E-04	100
Phenolic hardener	1.5	6.85 E-05	60
Butyl cellosolve acetate	1.0	4.57 E-05	40
Subtotal		4.57 E-03	3989

Molding Compound

Item	PPM	Method
Pb	Not Detected	Draft IEC 62321. ICP-OES.
Cd	Not Detected	Draft IEC 62321. ICP-OES.
Hg	Not Detected	Draft IEC 62321. ICP-OES.
Cr+6	Not Detected	Draft IEC 62321. UV-VIS.
PBB	Not Detected	Draft IEC 62321. GC-MS-D.
PBDE	Not Detected	Draft IEC 62321. GC-MS-D.

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	Draft IEC 62321. ICP-OES.
Cd	Not Detected	Draft IEC 62321. ICP-OES.
Hg	Not Detected	Draft IEC 62321. ICP-OES.
Cr+6	Not Detected	Draft IEC 62321. UV-VIS.
PBB	Not Detected	Draft IEC 62321. GC-MS-D.
PBDE	Not Detected	Draft IEC 62321. GC-MS-D.

Package Totals

Weight (g)	PPM
1.14 E+00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability tc any inaccuracy of such information.

ADI Proprietary

Materials Declaration

Package	PLCC
Body Size	
LeadCount	28
Option	with Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	72	5.66 E-01	575354
Epoxy Cresol Novolac	16	1.26 E-01	127856
Phenol Novolac	8	6.29 E-02	63928
Sb2O3	2.2	1.73 E-02	17580
Brominated Resin	1.6	1.26 E-02	12786
Carbon Black	0.2	1.57 E-03	1598
Subtotal		7.86 E-01	799102

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	99.9	1.59 E-01	161609
Zr	0.1	1.59 E-04	162
Subtotal		1.59 E-01	161770

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	1.21 E-03	1234

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	1.41 E-02	14308
Pb	15	2.48 E-03	2525
Subtotal		1.66 E-02	16833

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.41 E-03	1430

Chip

	% of Chip	Weight (g)	PPM
Si	100	1.56 E-02	15907

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag	80	2.93 E-03	2978
Epoxy Resin	15	5.49 E-04	558
Curing agent & hardener	5	1.83 E-04	186
Subtotal		3.66 E-03	3722

Package Totals

Weight (g)	PPM
9.84 E-01	1000000

Molding Compound

Item	PPM	Method
Pb	Not Detected	Draft IEC 62321. ICP-OES.
Cd	Not Detected	Draft IEC 62321. ICP-OES.
Hg	Not Detected	Draft IEC 62321. ICP-OES.
Cr+6	Not Detected	Draft IEC 62321. UV-VIS.
PBB	Not Detected	Draft IEC 62321. GC-MS-D.
PBDE	Not Detected	Draft IEC 62321. GC-MS-D.

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	Draft IEC 62321. ICP-OES.
Cd	Not Detected	Draft IEC 62321. ICP-OES.
Hg	Not Detected	Draft IEC 62321. ICP-OES.
Cr+6	Not Detected	Draft IEC 62321. UV-VIS.
PBB	Not Detected	Draft IEC 62321. GC-MS-D.
PBDE	Not Detected	Draft IEC 62321. GC-MS-D.

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability tc any inaccuracy of such information.

ADI Proprietary